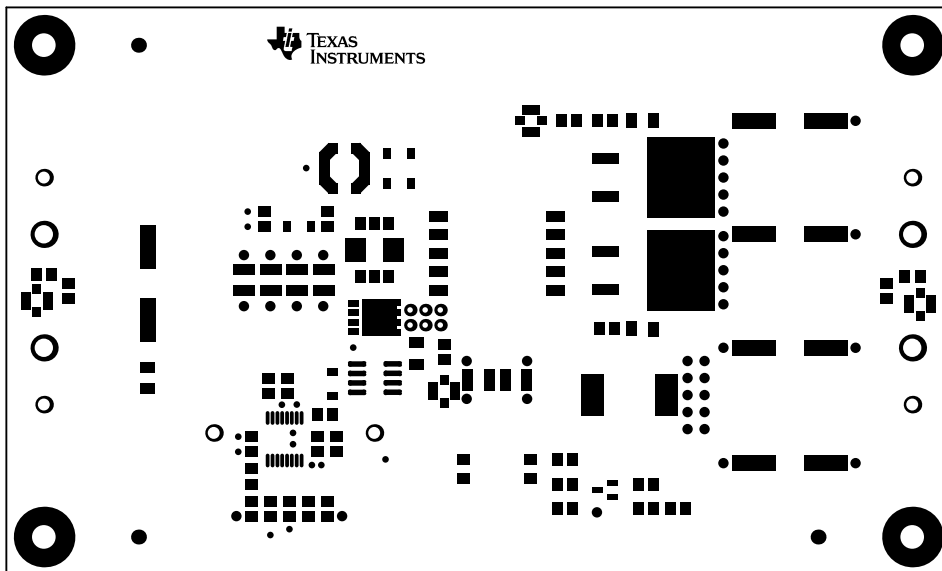
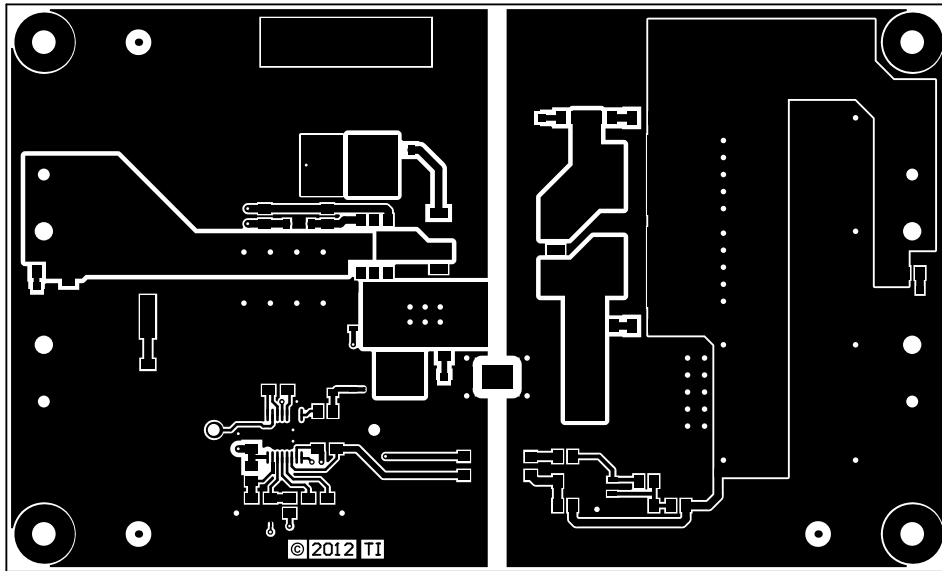


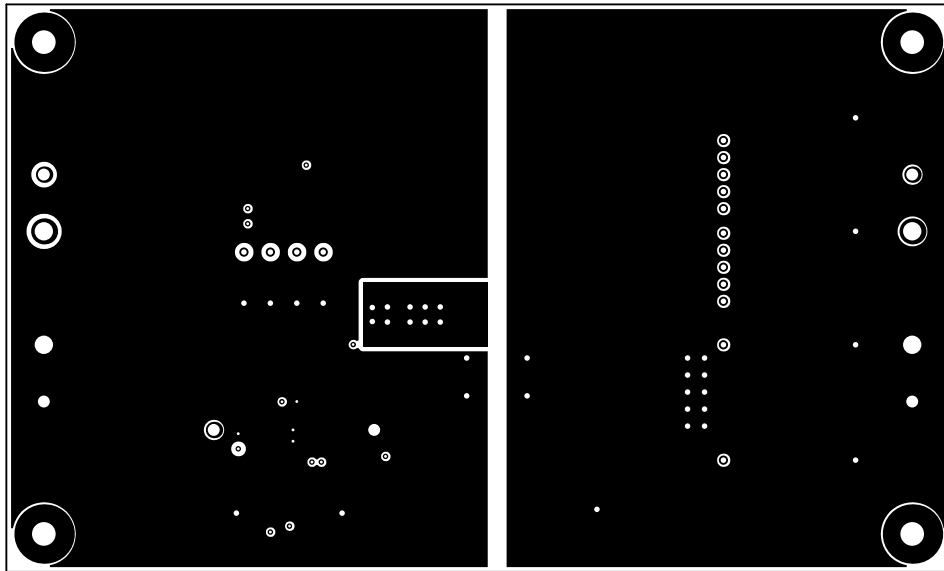
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/17/2012 4:53:55 PM	TEXAS INSTRUMENTS	



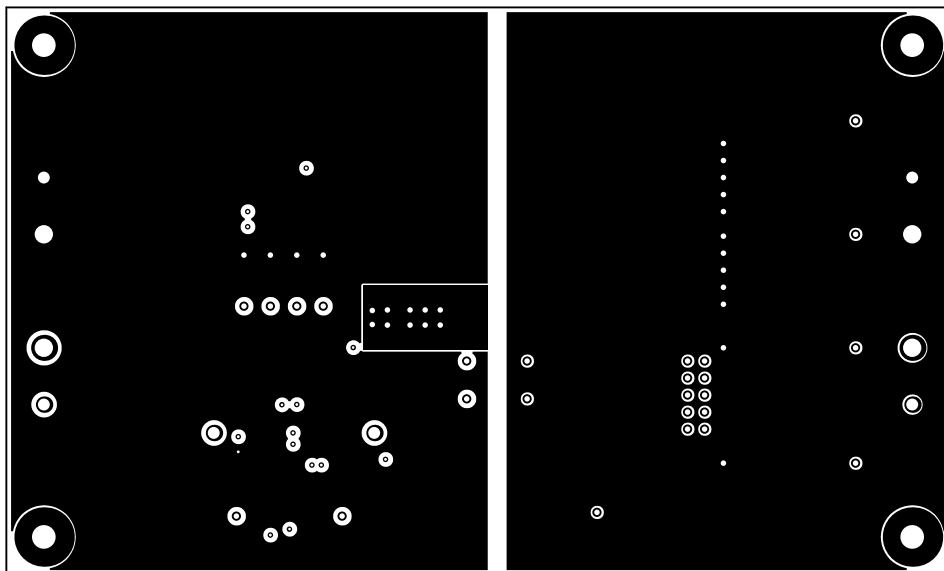
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/17/2012 4:53:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/17/2012 4:53:56 PM	TEXAS INSTRUMENTS	

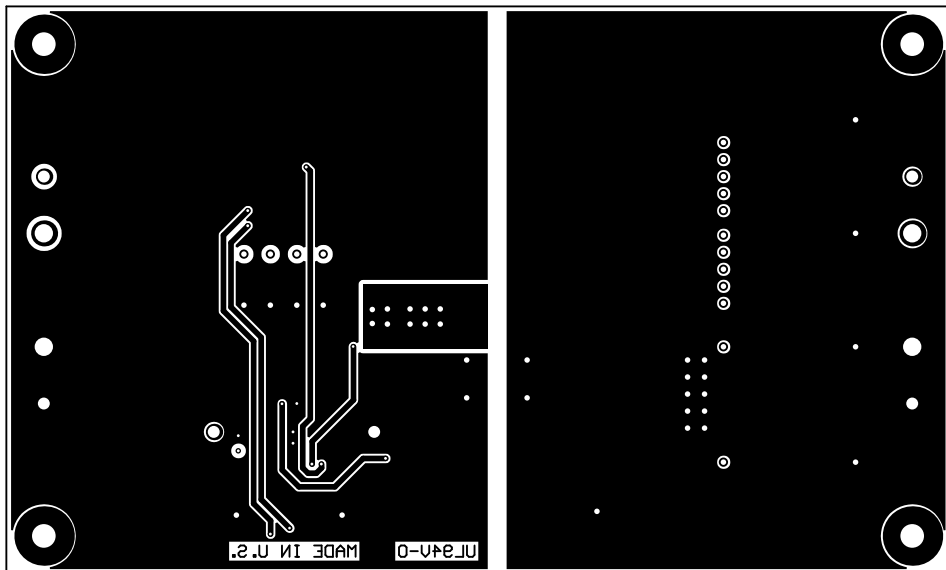


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 12/17/2012 4:53:57 PM	TEXAS INSTRUMENTS	

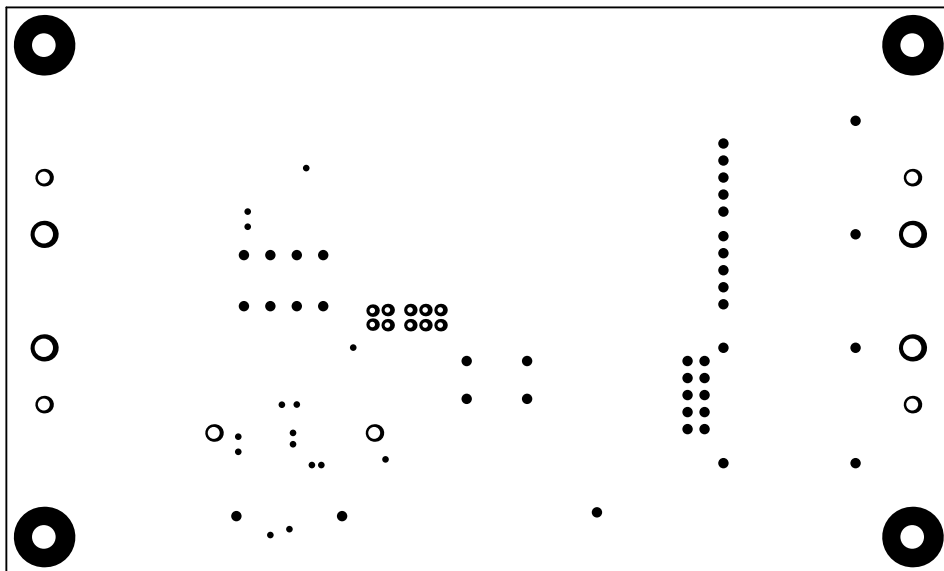


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 12/17/2012 4:53:58 PM	TEXAS INSTRUMENTS	

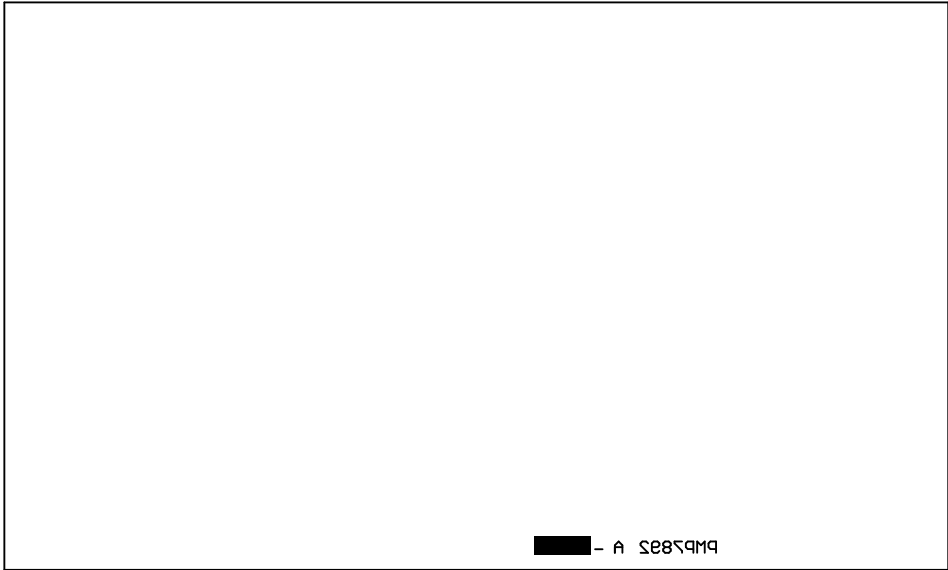
SUN REV: Not In VersionControl



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/17/2012 4:53:58 PM	TEXAS INSTRUMENTS	



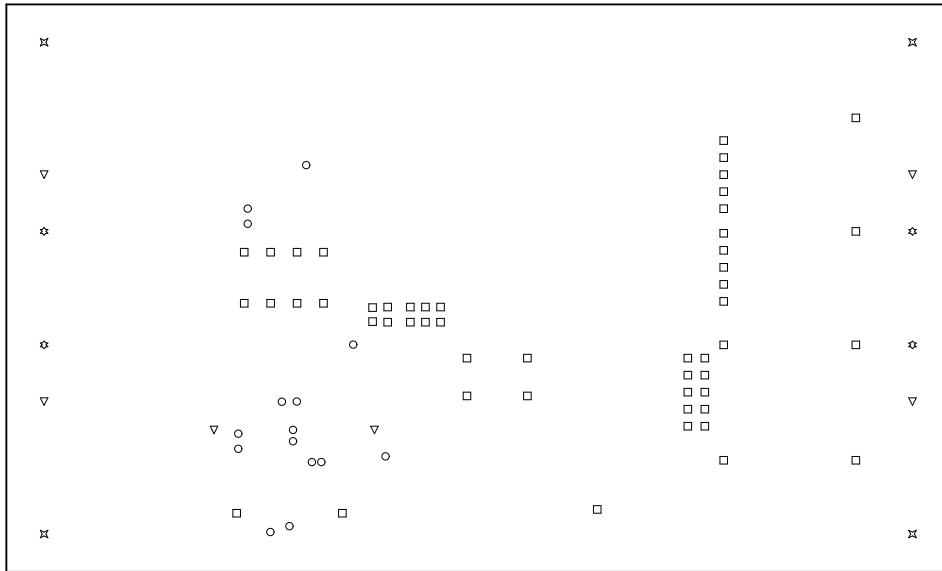
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/17/2012 4:53:59 PM	TEXAS INSTRUMENTS	



■ - A 28859M9

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/17/2012 4:53:59 PM	TEXAS INSTRUMENTS	

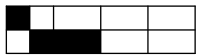
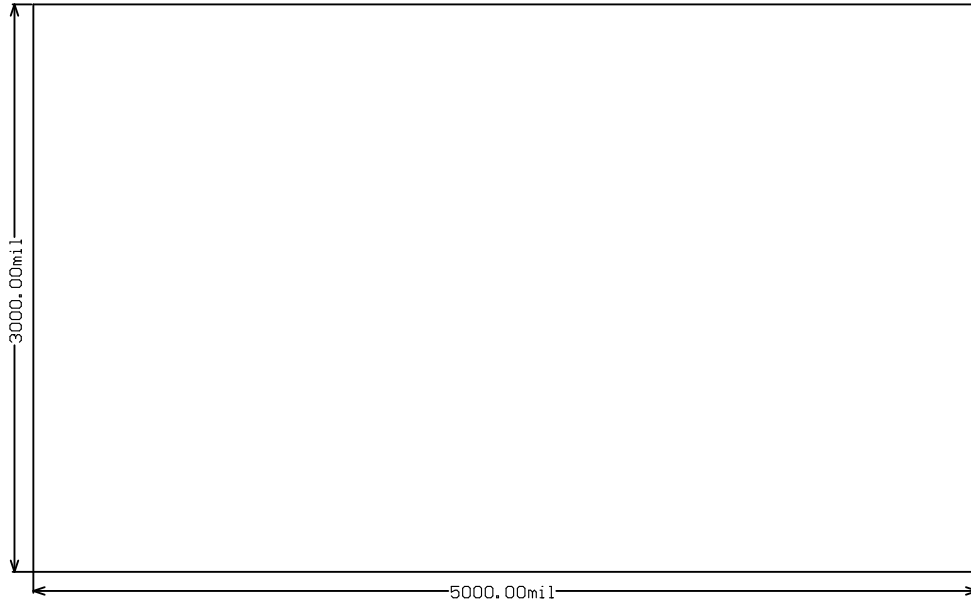




Symbol	Hit Count	Tool Size	Plated	Hole Type
○	15	15mil (0.381mm)	PTH	Round
□	51	30mil (0.762mm)	PTH	Round
▽	6	63mil (1.6mm)	PTH	Round
✱	4	98.425mil (2.5mm)	PTH	Round
⌘	4	125.984mil (3.2mm)	PTH	Round
	<b>80 Total</b>			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/17/2012 4:54:00 PM	TEXAS INSTRUMENTS	



← 1000 (mil) →

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/17/2012 4:54:00 PM	TEXAS INSTRUMENTS	

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